

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

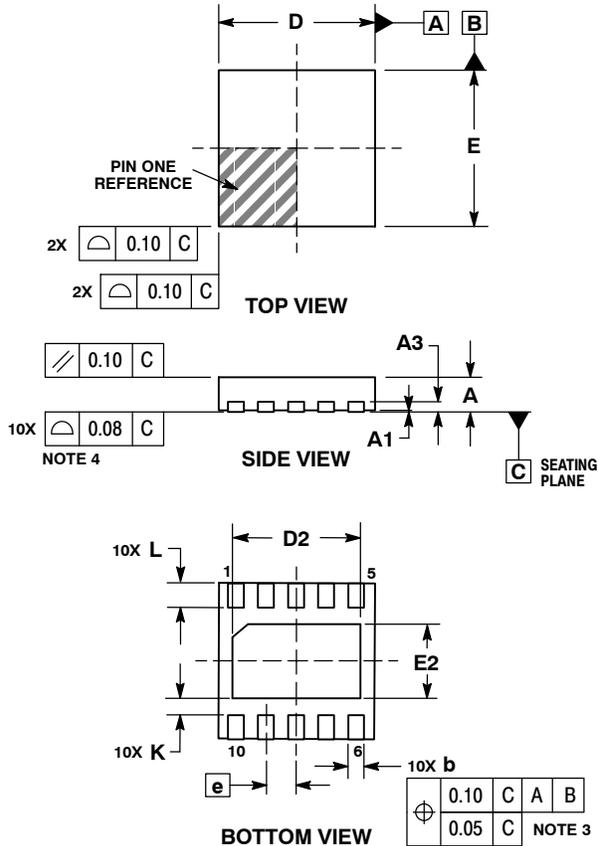
ON Semiconductor®



SCALE 2:1

UDFN10 2.6x2.6, 0.5P
CASE 517AN
ISSUE B

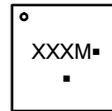
DATE 03 OCT 2012



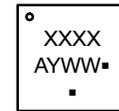
- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSION: MILLIMETERS.
 - DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.
 - COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.20	0.30
D	2.60 BSC	
D2	2.00	2.25
E	2.60 BSC	
E2	1.11	1.36
e	0.50 BSC	
K	0.20	---
L	0.30	0.40

GENERIC MARKING DIAGRAMS*



IC



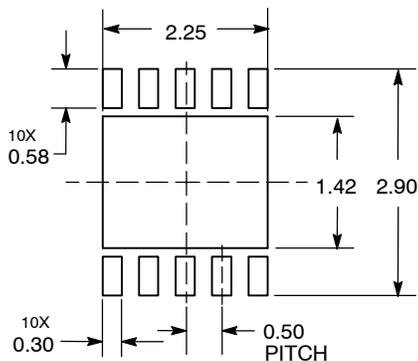
Discrete

- XXX = Specific Device Code
M = Month Code
▪ = Pb-Free Package
- XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

(*Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	UDFN10 2.6X2.6, 0.5P	PAGE 1 OF 2

